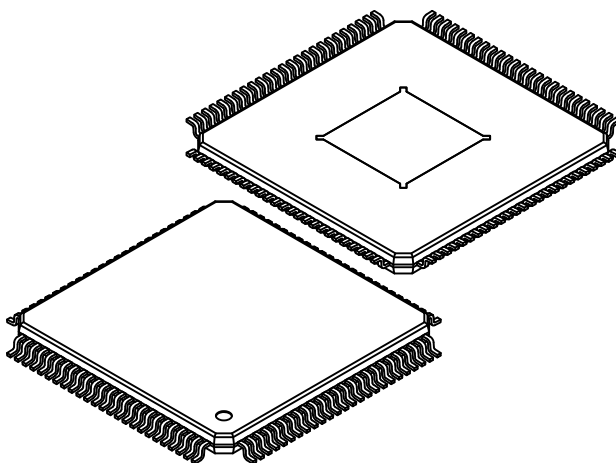
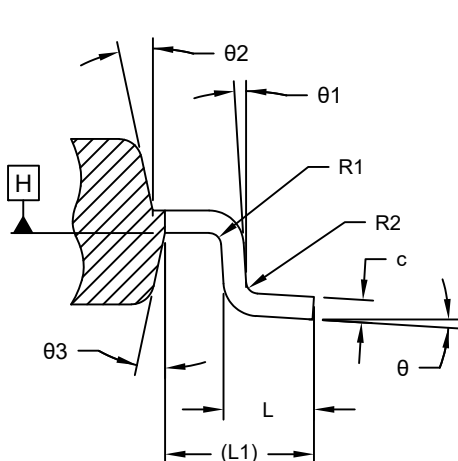


100-Lead Plastic Thin Quad Flat Pack (XEB) - 14x14x1.0 mm Body [TQFP] With 5.4 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



SECTION A-A

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		100		
Pitch	e		0.50 BSC		
Overall Height	A		-	-	1.20
Standoff	A1		0.05	-	0.15
Molded Package Thickness	A2		0.95	1.00	1.05
Overall Length	D		16.00 BSC		
Molded Package Length	D1		14.00 BSC		
Exposed Pad Length	D2		5.30	5.40	5.50
Overall Width	E		16.00 BSC		
Molded Package Width	E1		14.00 BSC		
Exposed Pad Width	E2		5.30	5.40	5.50
Terminal Width	b		0.17	0.22	0.27
Terminal Thickness	c		0.09	-	0.20
Terminal Length	L		0.45	0.60	0.75
Footprint	L1		1.00 REF		
Lead Bend Radius	R1		0.08	-	-
Lead Bend Radius	R2		0.08	-	0.20
Foot Angle	θ		0°	3.5°	7°
Lead Angle	$\theta 1$		0°	-	-
Mold Draft Angle	$\theta 2$		11°	12°	13°
Mold Draft Angle	$\theta 3$		11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.